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SEMELAB

T-39-13

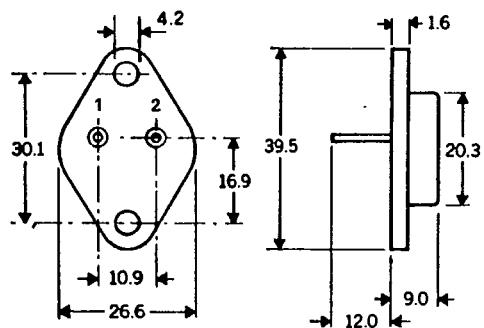
SMLB

REF BUP 60

T007 1400 REF BUP 62

MECHANICAL DATA

Dimensions in mm

**MOS POWER****N-Channel Enhancement Mode****APPLICATIONS**

- SWITCHING REGULATORS
- CONVERTERS
- MOTOR DRIVERS

PIN 1—Gate PIN 2—Source CASE—Drain

T03 Thin

ABSOLUTE MAXIMUM RATINGS (T_{CASE} = 25°C unless otherwise specified)

Parameter	BUP 60	BUP 62
V _{DS}	Drain source voltage	350V
V _{DGR}	Drain gate voltage (R _{GS} = 1 MΩ)	350V
I _D @ T _c = 25°C	Continuous drain current	±6.80A
I _D @ T _c = 100°C	Continuous drain current	±4.81A
I _{DM}	Pulsed drain current (i)	±16A
V _{GS}	Gate-source voltage	±40V
P _D @ T _c = 25°C	Maximum power dissipation	125W
P _D @ T _c = 100°C	Maximum power dissipation	62.5W
Junction to case	Linear derating factor	0.833 W/°C
Junction to ambient	Linear derating factor	0.03 W/°C
T _J	Operating and storage temperature range	-55 to 175°C
T _{stg}	(1/16" from case for 10 secs.)	300°C
Lead temperature		

(ii) Pulse test: Pulse width ≤ 300 μsec, duty cycle < 2%

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BUP 60 BUP 62

SEMELAB**ELECTRICAL CHARACTERISTICS (T_{CASE} = 25°C unless otherwise specified)****STATIC**

Parameter	Type	Min.	Typ.	Max.	Units	Test Conditions
BV _{DSS} Drain-Source Breakdown Voltage	BUP62	400	420		V	V _{GS} 0 I _D - 1 mA
	BUP60	350	370		V	V _{DS} V _{GS} , I _D - 1 mA V _{GS} +30V V _{GS} -30V
V _{GSt(h)} Gate-Threshold Voltage	All	3	4	6	V	V _{DS} V _{GS} , I _D - 1 mA
I _{GSSF} Gate-Body Leakage Forward	All		1	100	nA	V _{GS} +30V
I _{GSSR} Gate-Body Leakage Reverse	All		-1	-100	nA	V _{GS} -30V
I _{DSS} Zero Gate Voltage Drain Current	All		0.06	1	mA	V _{DS} Max. Rating, V _{GS} - 0
	All		0.13	2.5	mA	V _{DS} Max. Rating, V _{GS} - 0 T _C - 150°C
I _{D(on)} On-State Drain Current ¹	All	8	13		A	V _{DS} >2V _{DSON} , V _{GS} = 10V
V _{DSON} Static Drain-Source On State Voltage ¹	All		2.4	3	V	V _{GS} = 10V, I _D = 3A
R _{DSON} Static Drain-Source On State Resistance ¹	All		0.8	1	Ω	V _{GS} = 10V, I _D = 3A
R _{DSON} Static Drain-Source On State Resistance ¹	All		1.6	2	Ω	V _{GS} = 10V, I _D = 3A, T _C = 125°C

DYNAMIC

g _f	Forward Transductance ¹	All	2.5	3.5	S (if)	V _{DS} > 2V _{DSON} , I _D = 3A
C _{iss}	Input Capacitance	All	840	1000	pF	V _{GS} 0, V _{DS} = 25V
C _{oss}	Output Capacitance	All	150	220	pF	I = 1 MHz
C _{rss}	Reverse Transfer Capacitance	All	30	40	pF	V _{DD} = 200V, I _D = 3A
t _{d(on)}	Turn-On Delay Time	All	15	50	ns	R _g 10Ω, R _L 67Ω
t _r	Rise Time	All	20	50	ns	(MOS FET switching times are essentially independent of operating temperature.)
t _{d(off)}	Turn-Off Delay Time	All	50	100	ns	
t _f	Fall Time	All	50	80	ns	

THERMAL RESISTANCE

R _{thJC}	Junction-to-Case	All		1.2	C/W	
R _{thJA}	Junction-to-Ambient	All		33.4	C/W	Free Air Operation

BODY-DRAIN DIODE RATINGS AND CHARACTERISTICS

I _S	Continuous Source Current (Body Diode)	All		-6.8	A	Modified MOS POWER symbol showing the integral P-N junction rectifier. 
I _{SM}	Source Current ¹ (Body Diode)	All		-16	A	
V _{SD}	Diode Forward Voltage ¹	All		-0.9	V	T _C = 25°C, I _F = I _S ,
t _{rr}	Reverse Recovery Time	All		400	ns	T _J = 150°C, I _F = I _S , dI _F /dt = 100 A/μs

¹ Pulse Test: Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%

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